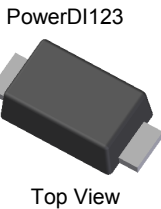


**Features**

- Ultra-Low Forward Voltage Drop
- Superior Reverse Avalanche Capability
- Patented Interlocking Clip Design for High Surge Current Capacity
- Patented Super Barrier Rectifier (SBR<sup>®</sup>) Technology
- Soft, Fast Switching Capability
- +150°C Operating Junction Temperature
- ±16KV ESD Protection (HBM, 3B)
- ±25KV ESD Protection (IEC61000-4-2 Level 4, Air Discharge)
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**
- **For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.**  
<https://www.diodes.com/quality/product-definitions/>

**Mechanical Data**

- Case: PowerDI<sup>®</sup>123
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity Indicator: Cathode Band
- Terminals: Matte Tin Finish Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 <sup>Ⓔ</sup>
- Weight: 0.018 grams (Approximate)

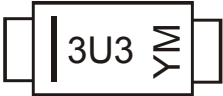


**Ordering Information** (Note 4)

Part Number	Case	Packaging
SBR3U30P1-7	PowerDI123	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3).compliant. All applicable RoHS exemptions applied.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>

**Marking Information**



3U3 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: G = 2019)  
 M = Month (ex: 9 = September)

Date Code Key

Year	2006	.....	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028
Code	T		G	H	I	J	K	L	M	N	O	P

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	30	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>RM</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	21	V
Average Rectified Output Current (See Figure 1)	I <sub>O</sub>	3.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms	I <sub>FSM</sub>	75	A
Single Half Sine-Wave Superimposed on Rated Load			
Non-Repetitive Avalanche Energy (T <sub>J</sub> = +25°C, I <sub>AS</sub> = 5A, L = 8.5mH)	E <sub>AS</sub>	105	mJ
Repetitive Peak Avalanche Energy (1μs, +25°C)	P <sub>ARM</sub>	1,100	W

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance	R <sub>θJS</sub>	5	°C/W
Thermal Resistance Junction to Soldering (Note 5)	R <sub>θJA</sub>	178	
Thermal Resistance Junction to Ambient (Note 6)	R <sub>θJA</sub>	123	
Thermal Resistance Junction to Ambient (Note 7)			
Operating and Storage Temperature Range (Note 8)	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V <sub>(BR)R</sub>	30	—	—	V	I <sub>R</sub> = 400μA
Forward Voltage Drop	V <sub>F</sub>	—	0.28	0.32	V	I <sub>F</sub> = 0.5A, T <sub>J</sub> = +25°C
			0.31	0.35		I <sub>F</sub> = 1.0A, T <sub>J</sub> = +25°C
			0.39	0.43		I <sub>F</sub> = 3.0A, T <sub>J</sub> = +25°C
			0.20	0.23		I <sub>F</sub> = 0.5A, T <sub>J</sub> = +125°C
			0.23	0.26		I <sub>F</sub> = 1.0A, T <sub>J</sub> = +125°C
0.35	0.38	I <sub>F</sub> = 3.0A, T <sub>J</sub> = +125°C				
Leakage Current (Note 8)	I <sub>R</sub>	—	70	150	μA	V <sub>R</sub> = 5V, T <sub>J</sub> = +25°C
			150	400	μA	V <sub>R</sub> = 30V, T <sub>J</sub> = +25°C
			6	15	mA	V <sub>R</sub> = 5V, T <sub>J</sub> = +125°C
			12	20	mA	V <sub>R</sub> = 30V, T <sub>J</sub> = +125°C

- Notes:
- Theoretical R<sub>θJS</sub> calculated from the top center of the die straight down to the PCB cathode tab solder junction.
  - FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
  - Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
  - Short duration pulse test used to minimize self-heating effect.

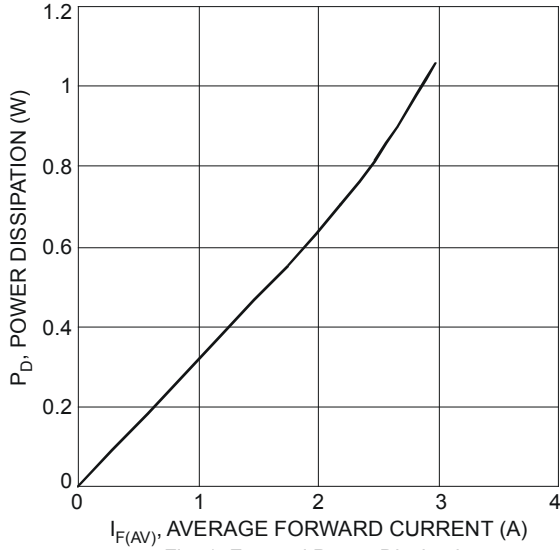


Fig. 1 Forward Power Dissipation

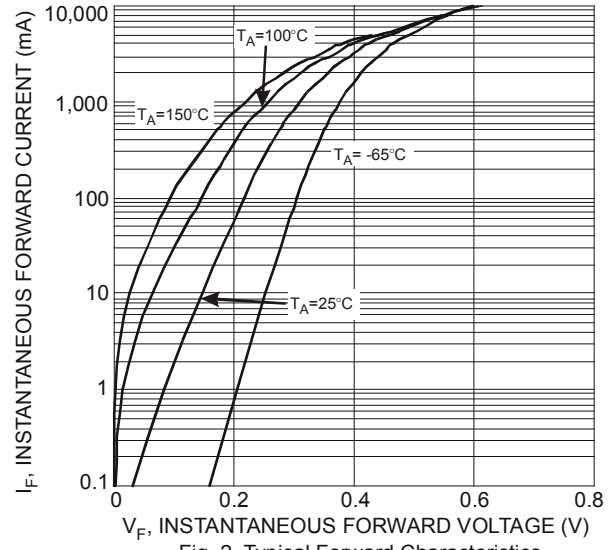


Fig. 2 Typical Forward Characteristics

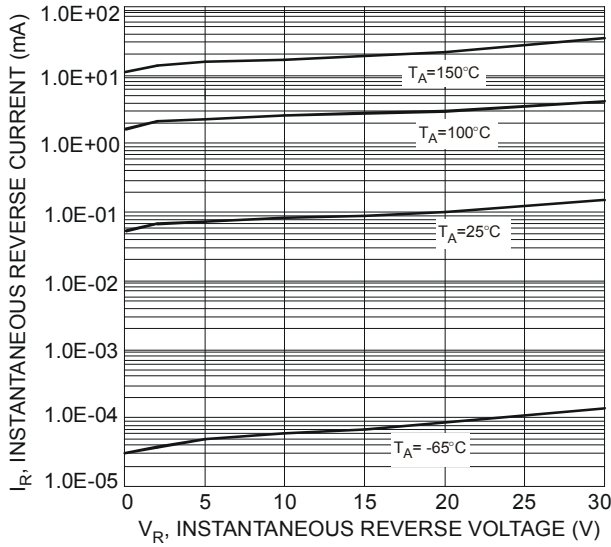


Fig. 3 Typical Reverse Characteristics

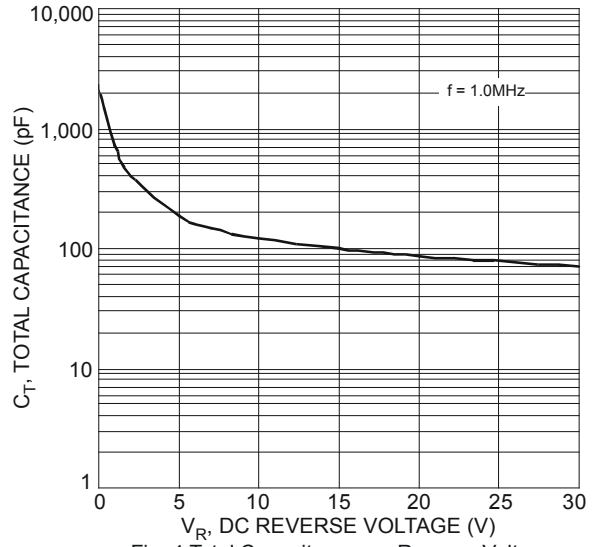


Fig. 4 Total Capacitance vs. Reverse Voltage

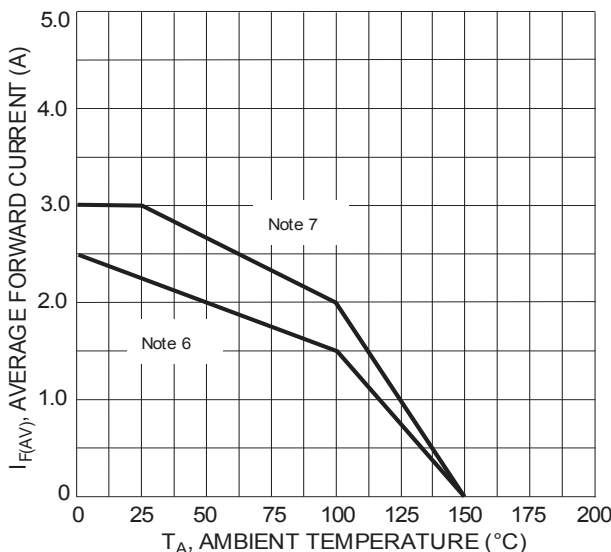


Fig. 5 Forward Current Derating Curve

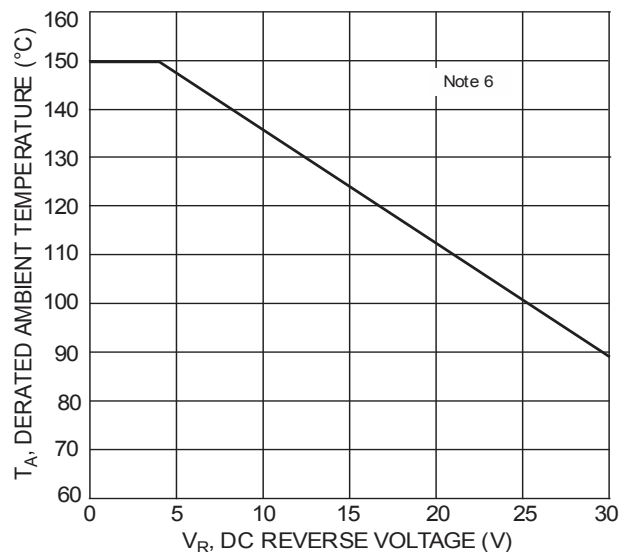


Fig. 6 Operating Temperature Derating

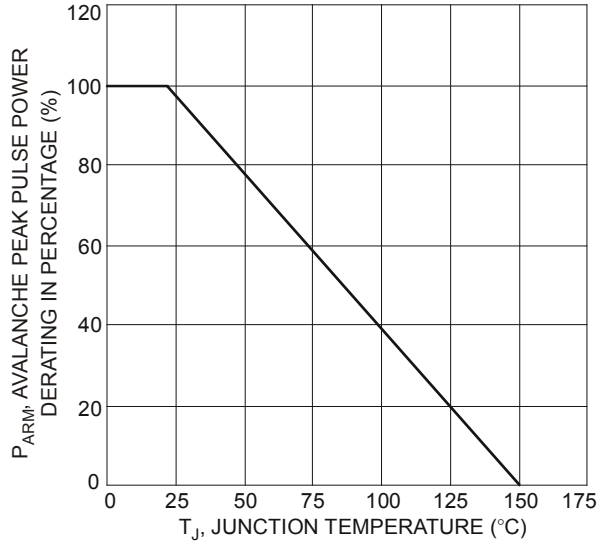


Fig. 7 Pulse Derating Curve

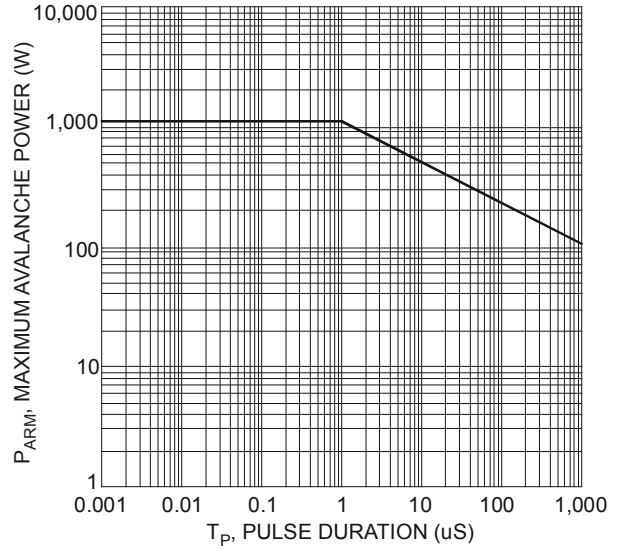


Fig. 8 Maximum Avalanche Power Curve

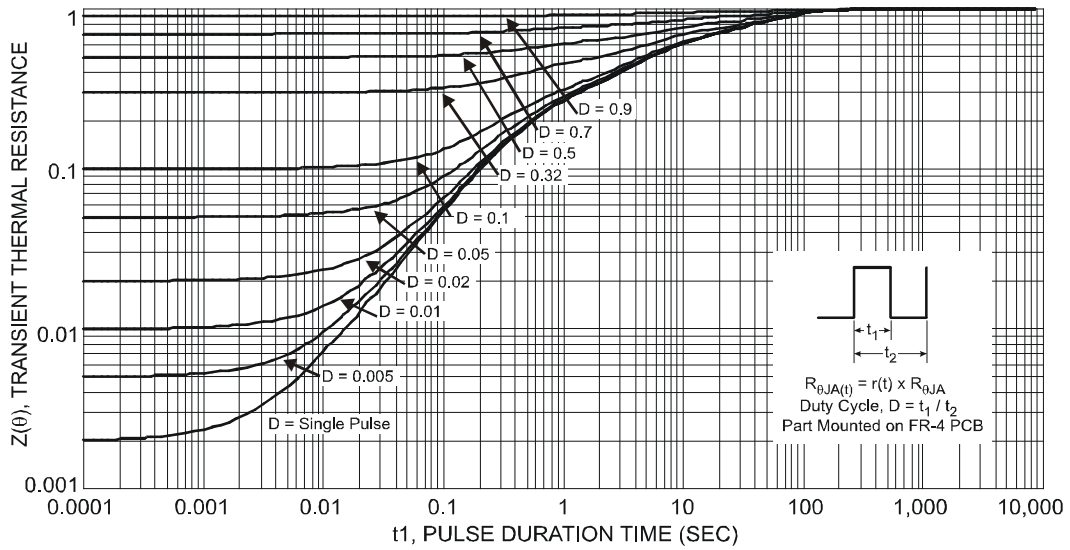
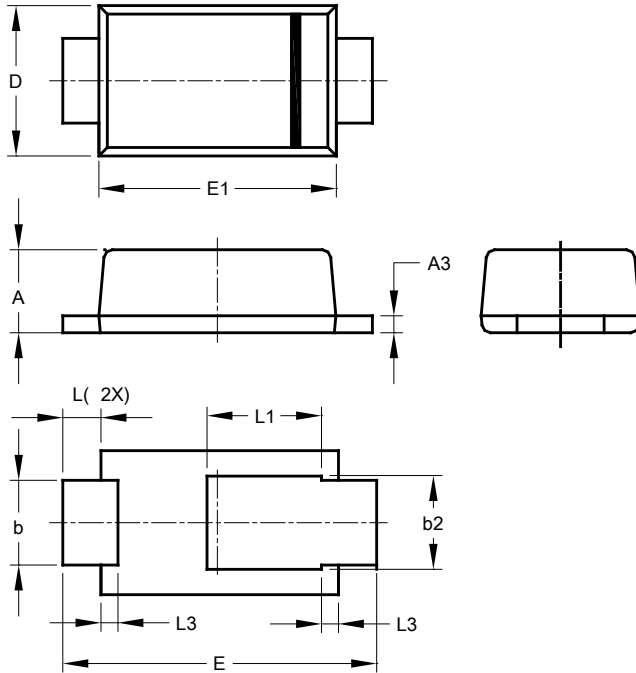


Fig. 9 Transient Thermal Resistance

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI123**

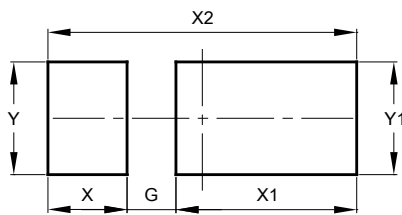


PowerDI123			
Dim	Min	Max	Typ
A	0.93	1.00	0.98
A3	0.15	0.25	0.20
b	0.85	1.25	1.00
b2	1.025	1.125	1.10
D	1.63	1.93	1.78
E	3.50	3.90	3.70
E1	2.60	3.00	2.80
L	0.40	0.50	0.45
L1	1.25	1.40	1.35
L3	0.125	0.275	0.20
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI123**



Dimensions	Value (in mm)
G	0.65
X	1.05
X1	2.40
X2	4.10
Y	1.50
Y1	1.50

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